# **Power MOSFET**

# -12 V, -7.0 A, Single P-Channel, 1.6x1.6x0.5 mm UDFN6 Package

#### **Features**

- Ultra Low R<sub>DS(on)</sub>
- UDFN Package with Exposed Drain Pads for Excellent Thermal Conduction
- Low Profile UDFN 1.6 x 1.6 x 0.5 mm for Board Space Saving
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

# **Applications**

- Optimized for Power Management Applications for Portable Products, Such as Smart Phones and Media Tablets
- Battery Switch
- High Side Load Switch

# MAXIMUM RATINGS (T<sub>J</sub> = 25°C unless otherwise stated)

Parameter			Symbol	Value	Unit	
Drain-to-Source Voltage			V <sub>DSS</sub>	-12	V	
Gate-to-Source Voltage			V <sub>GS</sub>	±8	V	
Continuous Drain	Steady	T <sub>A</sub> = 25°C	I <sub>D</sub>	-7.0	Α	
Current (Note 1)	State	T <sub>A</sub> = 85°C		-5.1		
	t ≤ 5 s	T <sub>A</sub> = 25°C		-10.5		
Power Dissipa- tion (Note 1)	Steady State	T <sub>A</sub> = 25°C	P <sub>D</sub>	1.71	W	
	t ≤ 5 s	T <sub>A</sub> = 25°C		3.83		
Continuous Drain	Steady	T <sub>A</sub> = 25°C	I <sub>D</sub>	-4.4	Α	
Current (Note 2)	State	T <sub>A</sub> = 85°C		-3.1		
Power Dissipation (Note 2) T <sub>A</sub> = 25°C		P <sub>D</sub>	0.66	W		
Pulsed Drain Current tp = 10 μs			I <sub>DM</sub>	-21	Α	
Operating Junction and Storage Temperature			T <sub>J</sub> , T <sub>STG</sub>	-55 to 150	°C	
Source Current (Body Diode) (Note 2)			Is	-1.7	Α	
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)				TL	260	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- Surface Mounted on FR4 Board using 1 in sq pad size (Cu area = 1.127 in sq [2 oz] including traces).
- Surface-mounted on FR4 board using the minimum recommended pad size of 30 mm<sup>2</sup>, 2 oz. Cu.

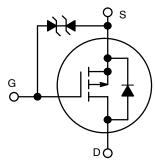


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#### **MOSFET**

V <sub>(BR)DSS</sub>	R <sub>DS(on)</sub> MAX	I <sub>D</sub> MAX	
	24 mΩ @ -4.5 V	-7.0 A	
-12 V	27 mΩ @ -3.7 V	-6.6 A	
	30 mΩ @ –3.3 V	-6.3 A	
	36 mΩ @ –2.5 V	-5.7 A	
	70 mΩ @ –1.8 V	-4.1 A	



P-Channel MOSFET

# MARKING DIAGRAM



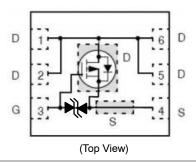
UDFN6 CASE 517AU



AA = Specific Device Code

(Note: Microdot may be in either location)

#### **PIN CONNECTIONS**



#### **ORDERING INFORMATION**

See detailed ordering and shipping information on page 5 of this data sheet.

# THERMAL RESISTANCE RATINGS

Parameter	Symbol	Max	Unit
Junction-to-Ambient – Steady State (Note 3)	$R_{\theta JA}$	72	
Junction-to-Ambient – t ≤ 5 s (Note 3)	$R_{\theta JA}$	32.6	°C/W
Junction-to-Ambient – Steady State min Pad (Note 4)	$R_{\theta JA}$	190.4	

- Surface-mounted on FR4 board using 1 in sq pad size (Cu area = 1.127 in sq [2 oz] including traces).
   Surface-mounted on FR4 board using the minimum recommended pad size of 30 mm², 2 oz. Cu.

# **ELECTRICAL CHARACTERISTICS** (T<sub>J</sub> = 25°C unless otherwise specified)

Parameter	Symbol	Test Condition		Min	Тур	Max	Units
OFF CHARACTERISTICS		•		•			
Drain-to-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$		-12			V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V <sub>(BR)DSS</sub> /T <sub>J</sub>	I <sub>D</sub> = -250 μA, ref to 25°C			7.3		mV/°C
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>GS</sub> = 0 V, V <sub>DS</sub> = -9.6 V	T <sub>J</sub> = 25°C			-1.0	μΑ
Gate-to-Source Leakage Current	I <sub>GSS</sub>	$V_{DS} = 0 V$ ,	V <sub>GS</sub> = ±8 V			±10	μΑ
ON CHARACTERISTICS (Note 5)							
Gate Threshold Voltage	V <sub>GS(TH)</sub>	$V_{GS} = V_{DS}$	I <sub>D</sub> = -250 μA	-0.4		-1.0	V
Negative Threshold Temp. Coefficient	V <sub>GS(TH)</sub> /T <sub>J</sub>				3.0		mV/°C
Drain-to-Source On Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = -4.5 \	V, I <sub>D</sub> = -7.0 A		20	24	mΩ
		$V_{GS} = -3.7$	V, I <sub>D</sub> = -6.6 A		22	27	
		V <sub>GS</sub> = −3.3 \	V, I <sub>D</sub> = -5.7 A		24	30	
		V <sub>GS</sub> = −2.5 \	V, I <sub>D</sub> = -5.1 A		29	36	
		V <sub>GS</sub> = -1.8 \	V, I <sub>D</sub> = -2.0 A		44	70	
Forward Transconductance	9FS	$V_{DS} = -5 \text{ V}, I_D = -7.0 \text{ A}$			21.8		S
CHARGES, CAPACITANCES & GATE	RESISTANCE						
Input Capacitance	C <sub>ISS</sub>	$V_{GS} = 0 \text{ V, f} = 1 \text{ MHz,}$ $V_{DS} = -6.0 \text{ V}$			1570		pF
Output Capacitance	C <sub>OSS</sub>				200		
Reverse Transfer Capacitance	C <sub>RSS</sub>	- 705 -	0.0 1		240		1
Total Gate Charge	Q <sub>G(TOT)</sub>				15.8		nC
Threshold Gate Charge	Q <sub>G(TH)</sub>	$V_{GS} = -4.5 \text{ V}, V_{DS} = -6.0 \text{ V};$ $I_{D} = -7.0 \text{ A}$			0.7		1
Gate-to-Source Charge	$Q_GS$				1.9		1
Gate-to-Drain Charge	$Q_{GD}$				4.6		1
SWITCHING CHARACTERISTICS (Not	te 6)			•	•	•	•
Turn-On Delay Time	t <sub>d(ON)</sub>				8.5		ns
Rise Time	t <sub>r</sub>	$V_{GS}$ = -4.5 V, $V_{DD}$ = -6 V, $I_{D}$ = -7.0 A, $R_{G}$ = 1 $\Omega$			52.5		
Turn-Off Delay Time	t <sub>d(OFF)</sub>				40		
Fall Time	t <sub>f</sub>				59		
DRAIN-SOURCE DIODE CHARACTER	RISTICS					•	•
Forward Diode Voltage	$V_{SD}$	V <sub>GS</sub> = 0 V,	T <sub>J</sub> = 25°C		0.71	1.0	V
		$I_{S} = -1.7 \text{ A}$	T <sub>.I</sub> = 125°C		0.58		1

- 5. Pulse Test: pulse width  $\leq$  300  $\mu$ s, duty cycle  $\leq$  2%.
- 6. Switching characteristics are independent of operating junction temperatures.

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

# **TYPICAL CHARACTERISTICS**

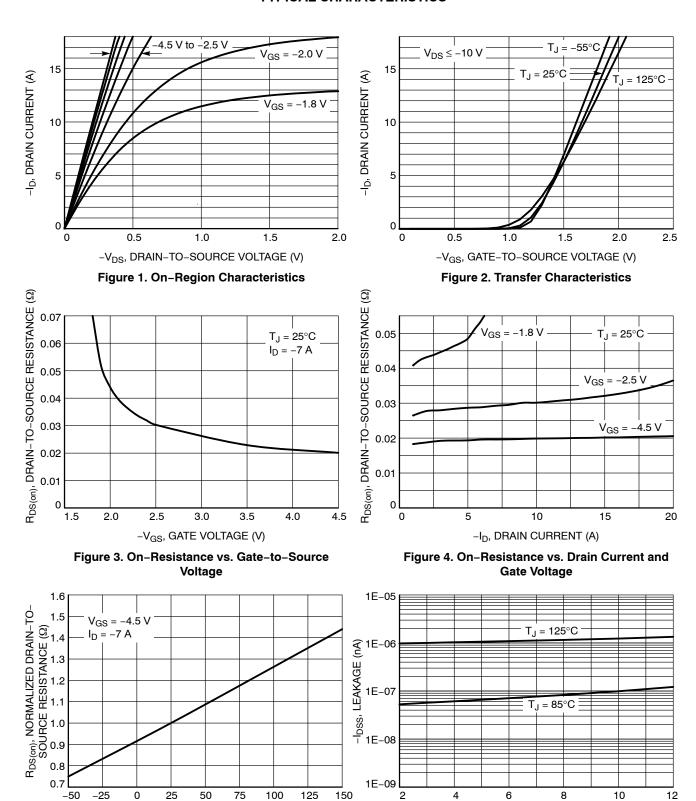


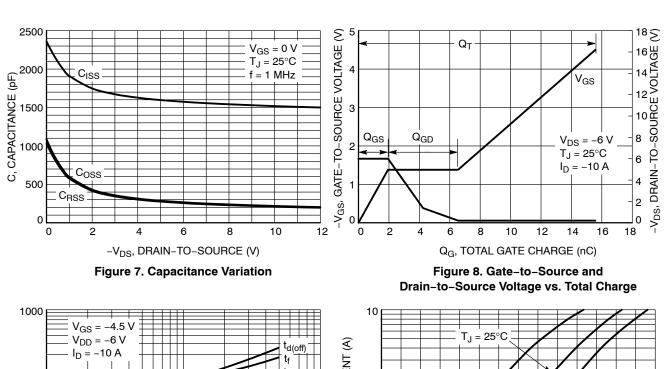
Figure 5. On–Resistance Variation with Temperature

T<sub>J</sub>, JUNCTION TEMPERATURE (°C)

Figure 6. Drain-to-Source Leakage Current vs. Voltage

-V<sub>DS</sub>, DRAIN-TO-SOURCE VOLTAGE (V)

# **TYPICAL CHARACTERISTICS**



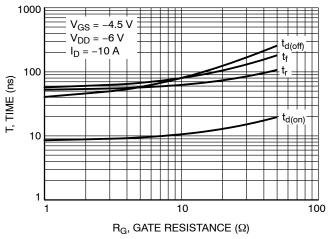


Figure 9. Resistive Switching Time Variation vs. Gate Resistance

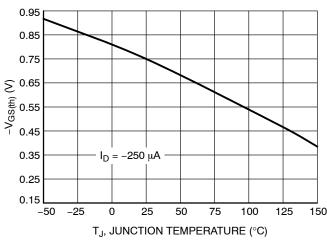


Figure 11. Threshold Voltage

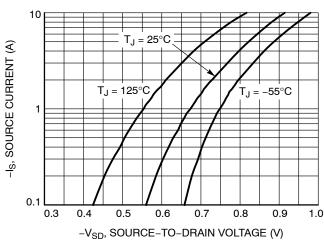


Figure 10. Diode Forward Voltage vs. Current

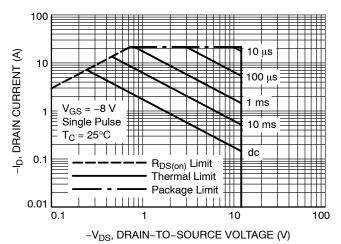


Figure 12. Maximum Rated Forward Biased Safe Operating Area

# **TYPICAL CHARACTERISTICS**

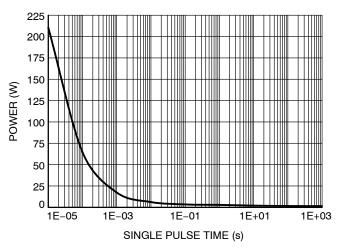


Figure 13. Single Pulse Maximum Power Dissipation

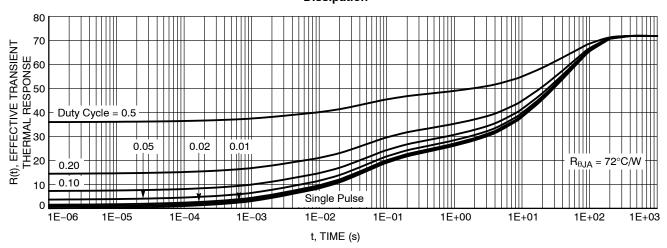


Figure 14. FET Thermal Response

#### **DEVICE ORDERING INFORMATION**

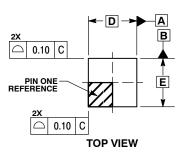
Device	Package	Shipping <sup>†</sup>
NTLUS3C18PZTAG	UDFN6 (Pb-Free)	3000 / Tape & Reel
NTLUS3C18PZTBG	UDFN6 (Pb-Free)	3000 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

#### PACKAGE DIMENSIONS

# UDFN6 1.6x1.6, 0.5P CASE 517AU

**ISSUE O** 



DETAIL B

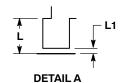
SIDE VIEW

0.05 C

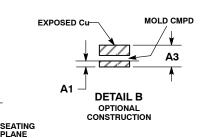
0.05 C

 $|\triangle|$ 

NOTE 4



OPTIONAL CONSTRUCTION



#### NOTES

- NOTES:

  1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.

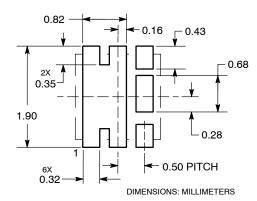
  2. CONTROLLING DIMENSION: MILLIMETERS.

  3. DIMENSION 5 APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND
- 0.30 mm FROM TERMINAL. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

	MILLIMETERS		
DIM	MIN	MAX	
Α	0.45	0.55	
A1	0.00	0.05	
А3	0.13 REF		
b	0.20	0.30	
D	1.60 BSC		
Е	1.60 BSC		
е	0.50 BSC		
D1	0.62 0.72		
D2	0.15	0.25	
E2	0.57	0.67	
F	0.55 BSC		
G	0.25 BSC		
L	0.20	0.30	
L1		0.15	

#### С Α В 0.10 0.10 | C | A | B Ф DETAIL A CAB D1 0.10 Ф C NOTE 3 0.05 **BOTTOM VIEW**

#### SOLDERMASK DEFINED **MOUNTING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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